



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D

*\* : Required Field*

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2015-09-17
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	LAURENT TOSI	<b>Representative Title</b>	MMS MD CHAMPION
<b>Representative Phone *</b>	33 442 685 795	<b>Representative Email *</b>	<a href="mailto:laurent.tosi@st.com">laurent.tosi@st.com</a>
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/online_tech_support.html">http://www.st.com/web/en/support/online_tech_support.html</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32L052T8Y6TR	H02A*417CCCZ	A	9989	2015-09-17
Amount		UoM	Unit type	ST ECOPACK Grade
8.544		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
SACN125	NAC	NAC		

Package Designator	Size	Nbr of instances	Shape	
BGA	NAC	36	No lead	
Comment	Package: WLCSP 36L DIE 417 P 0.4MM		Package: WLCSP 36L DIE 417 P 0.4MM	

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	<b>true</b>
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-15th June 2015				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				<b>true</b>
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	HOZA*417CCCZ					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies	Other inorganic materials	6.169	mg	supplier	die	Silicon (Si)	7440-21-3		5.921	mg	959799	693001
Die or Dies					metallization	Aluminium (Al)	7429-90-5		0.019	mg	3080	2224
Die or Dies					metallization	Copper (Cu)	7440-50-8		0.062	mg	10050	7257
Die or Dies					metallization	Tantalum (Ta)	7440-25-7		0.043	mg	6970	5033
Die or Dies					metallization	Titanium (Ti)	7440-32-6		0.009	mg	1459	1053
Die or Dies					passivation	Silicon Nitride (SiN)	68034-42-4		0.016	mg	2594	1873
Die or Dies					passivation	Silicon Oxide (SiO2)	7631-86-9		0.099	mg	16048	11587
Coating-P11-Hitachi Chemical,HD4100	Other inorganic materials	0.040	mg	supplier	Plastics/polymers	PD-9 Resin	Proprietary		0.028	mg	700000	3277
Coating-P11-Hitachi Chemical,HD4100					Organic compounds	Trifluoroacetic Anhydride	407-25-0		0.002	mg	50000	234
Coating-P11-Hitachi Chemical,HD4100					Acrylates	Tetraethylene Glycol Dimethacrylate	109-17-1		0.006	mg	150000	702
Coating-P11-Hitachi Chemical,HD4100					Organic compounds	4,4'-Oxydipthalic Anhydride	1823-59-2		0.002	mg	50000	234
Coating-P11-Hitachi Chemical,HD4100					Acrylates	2-Hydroxyethyl Methacrylate	868-77-9		0.002	mg	50000	234
Coating-P12-Hitachi Chemical,HD4100					Plastics/polymers	PD-9 Resin	Proprietary		0.024	mg	685714	2809
Coating-P12-Hitachi Chemical,HD4100	Other inorganic materials	0.035	mg	supplier	Organic compounds	Trifluoroacetic Anhydride	407-25-0		0.002	mg	57143	234
Coating-P12-Hitachi Chemical,HD4100					Acrylates	Tetraethylene Glycol Dimethacrylate	109-17-1		0.005	mg	142857	585
Coating-P12-Hitachi Chemical,HD4100					Organic compounds	4,4'-Oxydipthalic Anhydride	1823-59-2		0.002	mg	57143	234
Coating-P12-Hitachi Chemical,HD4100					Acrylates	2-Hydroxyethyl Methacrylate	868-77-9		0.002	mg	57143	234
RDL-Ti Target	Other inorganic materials	0.001	mg	supplier	Alloy	Titanium	7440-32-6		0.001	mg	1000000	117
RDL-Cu Target	Other inorganic materials	0.003	mg	supplier	Alloy	Copper	7440-50-8		0.003	mg	1000000	351
RDL-Cu Anode	Other inorganic materials	0.042	mg	supplier	Alloy	Copper	7440-50-8		0.042	mg	1000000	4916
UBM-Ti Target	Other inorganic materials	0.001	mg	supplier	Alloy	Titanium	7440-32-6		0.001	mg	1000000	117
UBM-Cu Target	Other inorganic materials	0.006	mg	supplier	Alloy	Copper	7440-50-8		0.006	mg	1000000	702
UBM-Cu Anode	Other inorganic materials	0.251	mg	supplier	Alloy	Copper	7440-50-8		0.251	mg	1000000	29377
Solder Ball-Senju,Sn98.25 Ag1.2 Cu0.5	Other inorganic materials	1.687	mg	supplier	Solder	Tin	7440-31-5		1.658	mg	982810	194054
Solder Ball-Senju,Sn98.25 Ag1.2 Cu0.5					Solder	Silver	7440-22-4		0.020	mg	11855	2341
Solder Ball-Senju,Sn98.25 Ag1.2 Cu0.5					Solder	Copper	7440-50-8		0.008	mg	4742	936
Solder Ball-Senju,Sn98.25 Ag1.2 Cu0.5					Solder	Nickel	7440-02-0		0.001	mg	593	117
Backside Tape-LC2850	Other inorganic materials	0.309	mg	supplier	Polymers	Silica (Adhesive)	Trade Secret		0.174	mg	563107	20365
Backside Tape-LC2850					Polymers	Epoxy resin (adhesive)	Trade Secret		0.065	mg	210356	7608
Backside Tape-LC2850					Polymers	Acrylic resin (adhesive) black	Trade Secret		0.065	mg	210356	7608
Backside Tape-LC2850					Polymers	Carbon black	Trade Secret		0.005	mg	16181	585